International Workshop on
Software Engineering and Knowledge Management (SEKM 2020)
December 11-14, 2020
Macau, China

In conjunction with the 20th IEEE International Conference
on Software Quality, Reliability, and Security (QRS 2020)

Call for Papers
The SEKM 2020 workshop aims at bringing together experts in software engineering and knowledge management to discuss on relevant results in either software engineering or knowledge management or both. Special emphasis will be put on the transference of methods between both domains.

The topics of interest include (but not limited to):
• Software engineering practice
• Web engineering
• Software maintenance and testing
• Formal methods
• Domain engineering
• Software product line
• Ontology and methodology
• Big data
• Web-based education systems and learning applications
• Software engineering decision making
• Search engines and information retrieval
• Requirements engineering
• Cloud computing
• Knowledge representation and reasoning
• Formal analysis of knowledge and logics of knowledge
• Knowledge in complex systems and multi-agent systems
• Knowledge extraction and knowledge integration
• Knowledge-based software engineering
• Knowledge-based and expert system
• Complex system modeling and complexity
• Decision analysis and decision support systems
• Knowledge discovery, data mining, text mining, recommendation system
• Knowledge management strategies and practices
• Web-based knowledge management
Important Dates

- June 15, 2020  Submission deadline
- July 10, 2020  Author notification

Workshop Chairs

- Guoqiang Li, Shanghai Jiao Tong University, China (li.g@sjtu.edu.cn)
- Xingya Wang, Nanjing Tech University, China (xingyawang@outlook.com)

Program Committee

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- Chunhui Yang, China Electronic Product Reliability and Environmental Testing Research Institute (CEPREI), China
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- Haitao Zhang, Japan Advanced Institute of Science and Technology, Japan
- Min Zhang, East China Normal University, China
- Dongdong Zhao, Wuhan University of Technology, China
- Zheng Zheng, Beihang University, China